

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 60100457
PUBLICATION DATE : 04-06-85

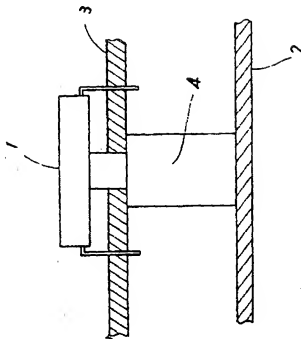
APPLICATION DATE : 04-11-83
APPLICATION NUMBER : 58207875

APPLICANT : MATSUSHITA ELECTRIC IND CO LTD;

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INT.CL. : H01L 23/36 H05K 7/20

TITLE : HEAT SINK DEVICE OF ELECTRONIC
COMPONENT



ABSTRACT : PURPOSE: To enable to reduce the size of a heat sink device of an electronic component by interposing a thermal conductive member between the component and a metal case to enable to efficiently dissipate the heat of the component by utilizing the wide surface of the case, thereby eliminating the necessity of a bulky heat sink plate.

CONSTITUTION: A thermal conductive member 4 is interposed between an electronic component 1 and a metal case 2 in which the component 1 is arranged. For example, a thermal conductive metal post 4 interposed between the component 1 and the case 2 is contacted with the side surface of the component 1 on the face of one end which passes a circuit board 3, and with the inner surface of the case 2 on the face of the other end. The heat generated from the component 1 is transmitted to the case 2 through the post 4, and efficiently dissipated from the wide surface, thereby holding the component 1 at the prescribed temperature or lower.

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